

SOT1384-5

wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm
x 0.525 mm body (backside coating included)

8 August 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP9
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	08-08-2018
Manufacturer package code	SOT1384

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.21	1.24	1.27	mm
package width	1.21	1.24	1.27	mm
seated height	0.485	0.525	0.565	mm
nominal pitch	-	0.4	-	mm



wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm x 0.525 mm body (backside coating included)

2 Package outline

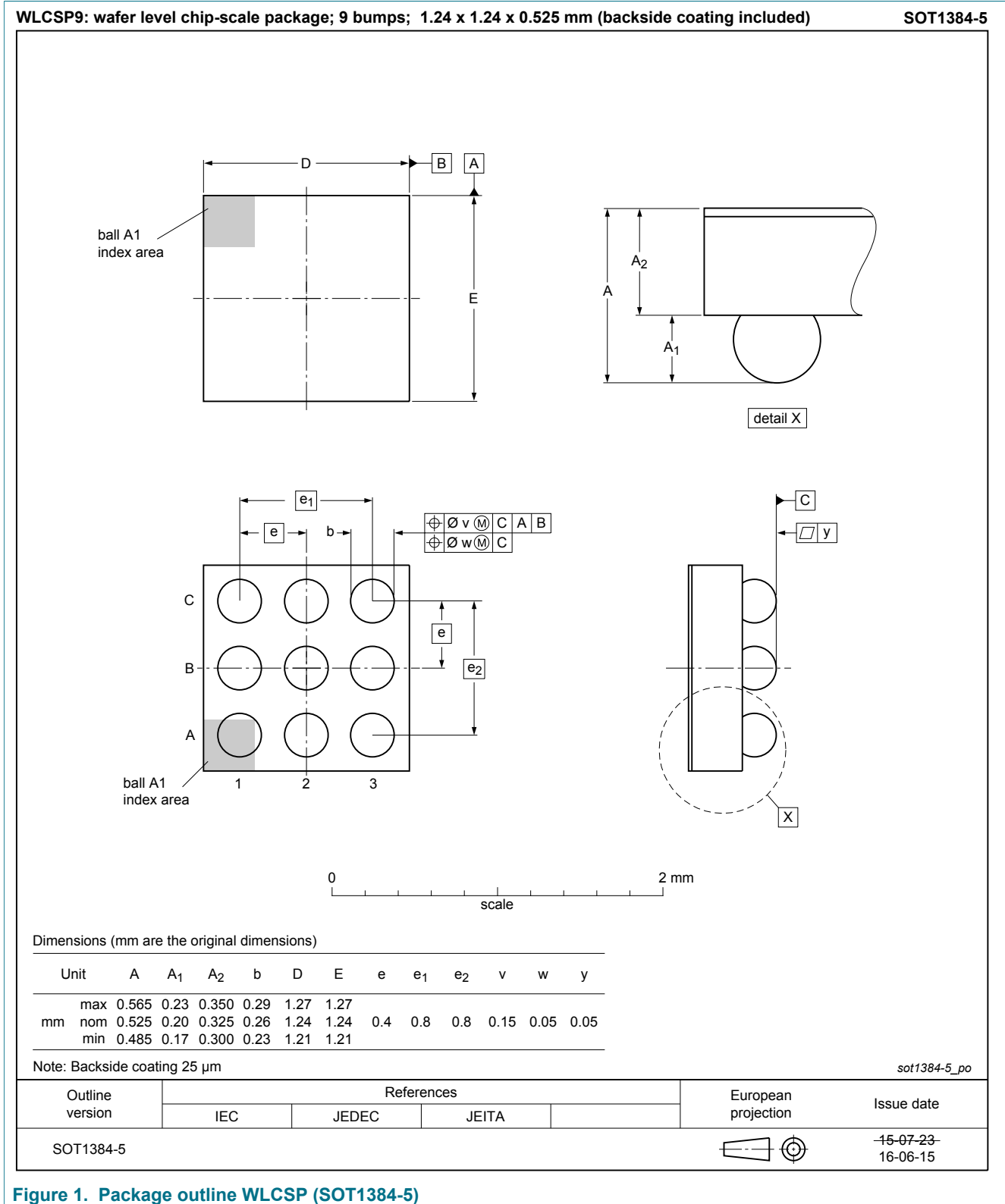


Figure 1. Package outline WLCSP (SOT1384-5)

wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm x 0.525 mm body (backside coating included)

3 Soldering

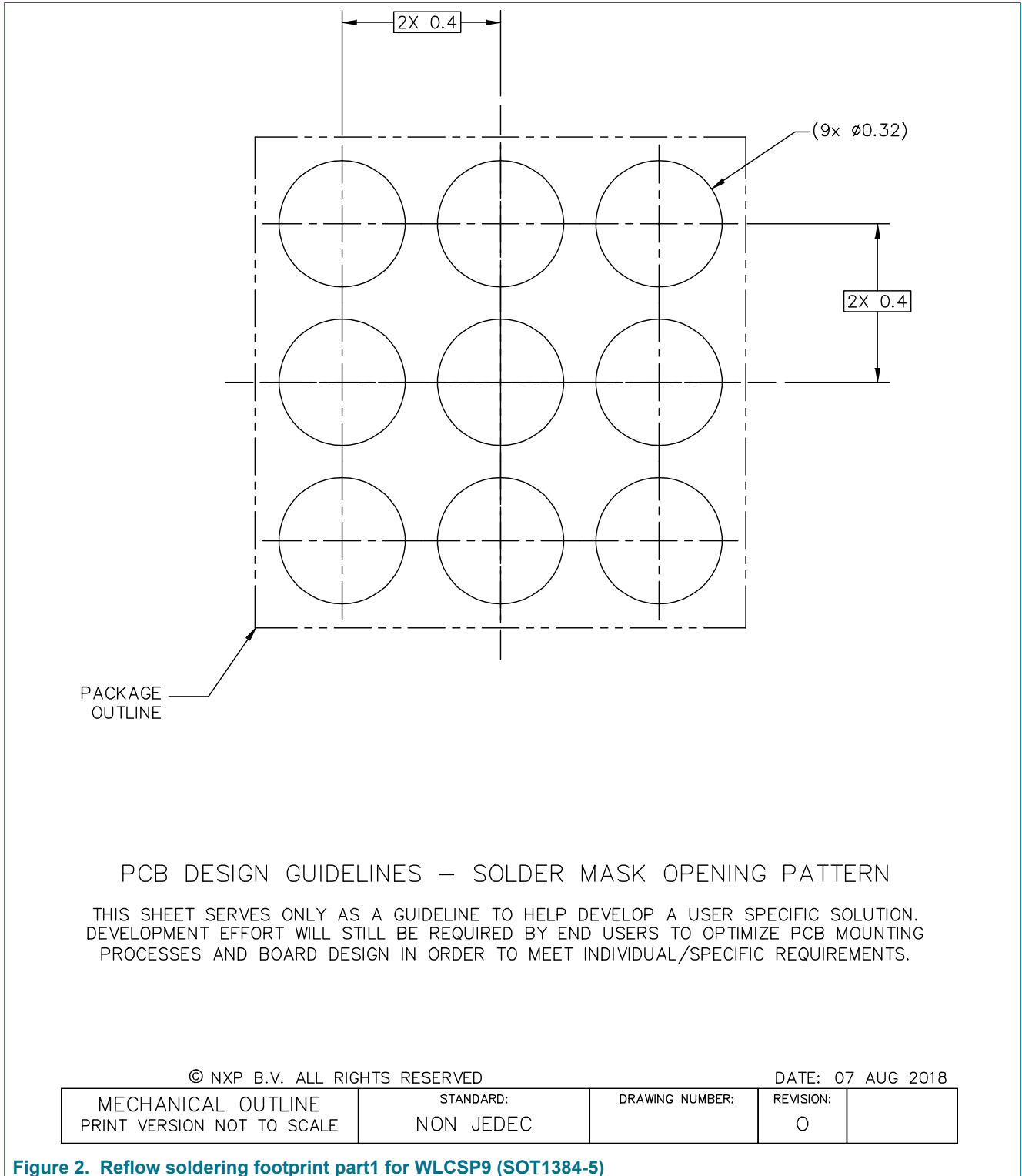


Figure 2. Reflow soldering footprint part1 for WLCSP9 (SOT1384-5)

wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm x 0.525 mm body (backside coating included)

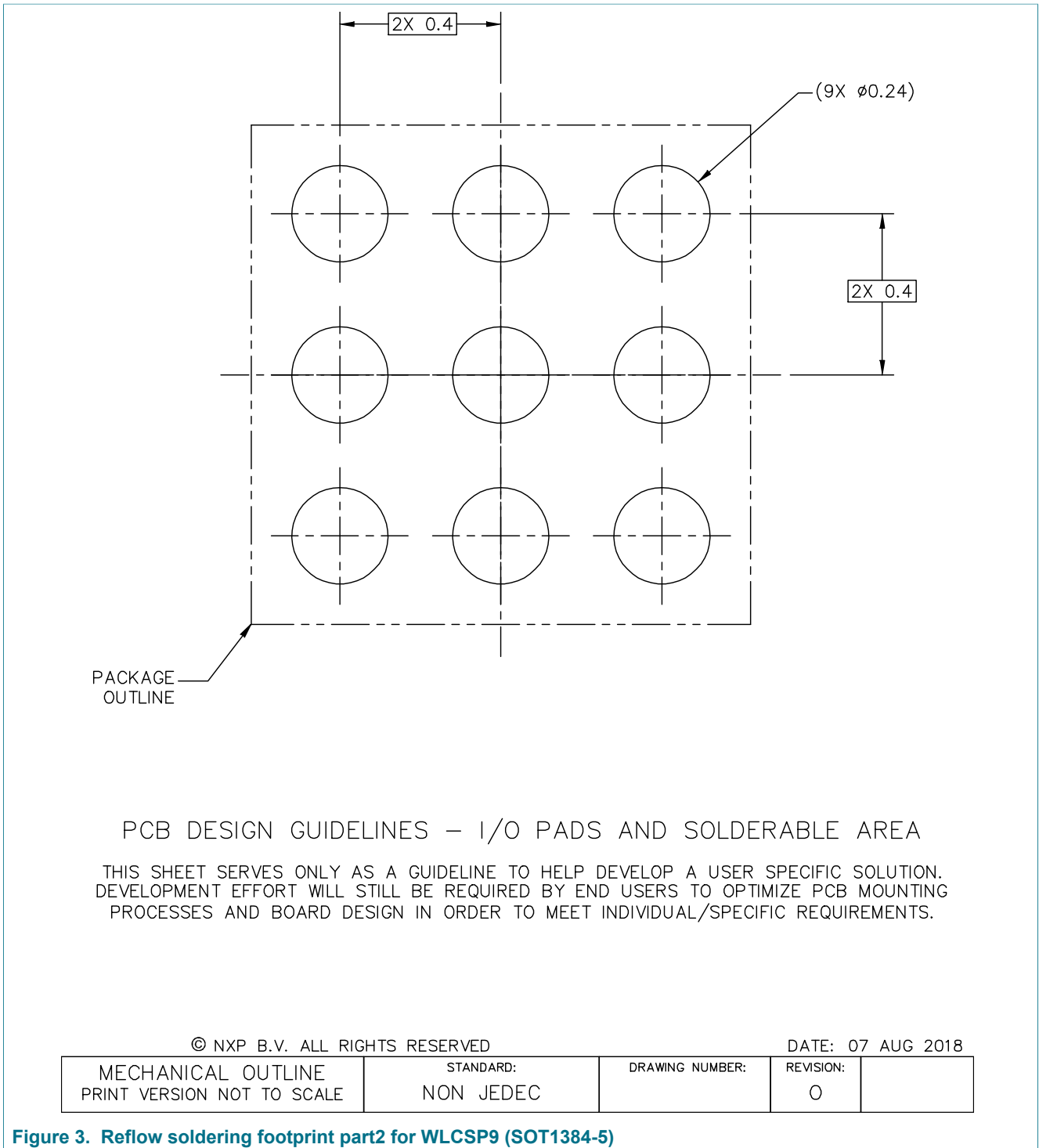


Figure 3. Reflow soldering footprint part2 for WLCSP9 (SOT1384-5)

wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm x 0.525 mm body (backside coating included)

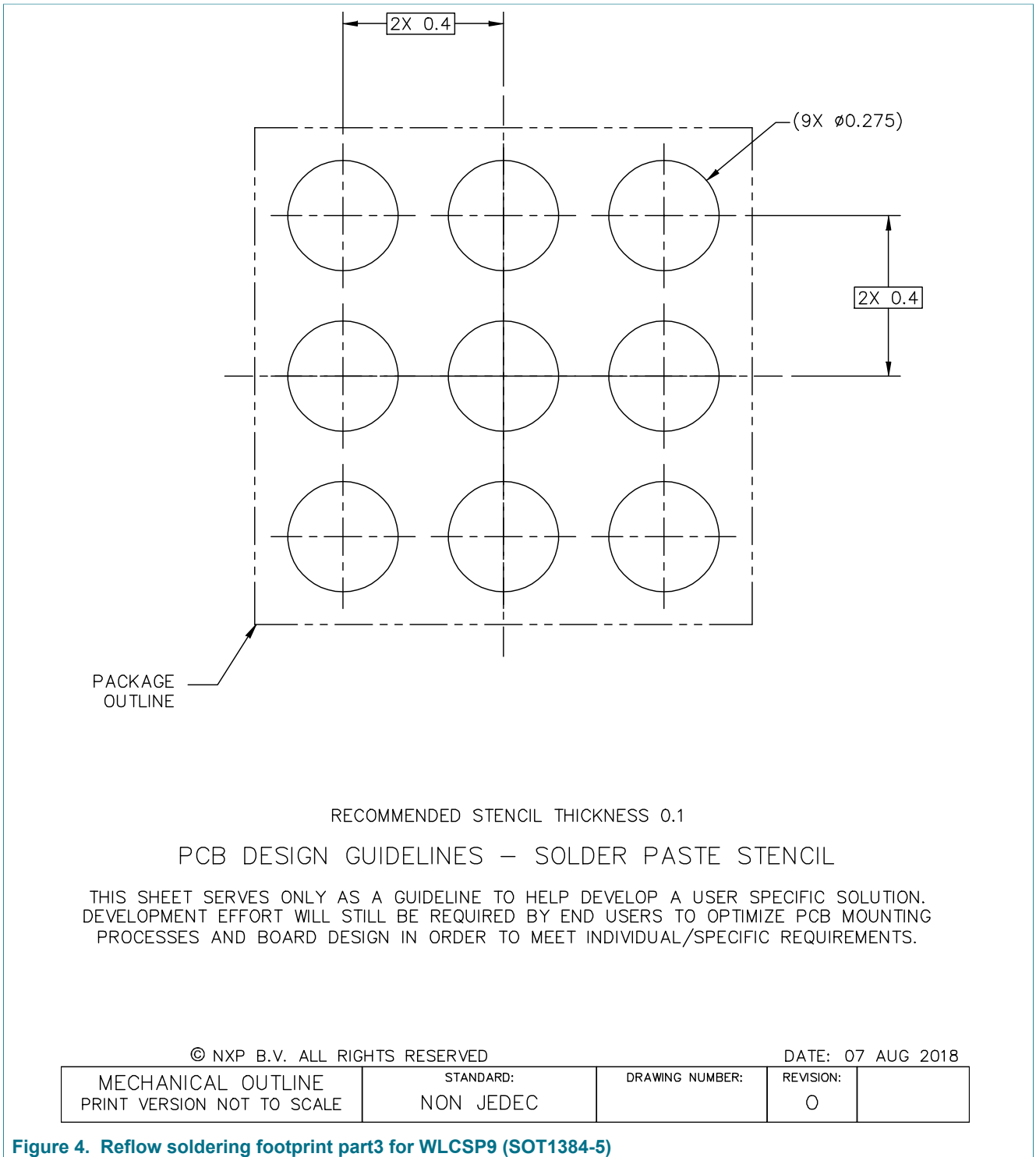


Figure 4. Reflow soldering footprint part3 for WLCSP9 (SOT1384-5)

wafer level chip-scale package; 9 bumps; 1.24 mm x 1.24 mm x 0.525 mm body (backside coating included)

4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering3
4 Legal information6